

AMI 7300 MICROPROCESSOR  
ELECTRICAL CHARACTERISTICS

4/10/73

## MIR + RALU

0.0 MINIMUMS NOT SPECIFIED ARE 0 (ZERO)

0.0.1 All specifications, unless otherwise specified, are total values for both chips, and are specified over the total operating temperature range.

### 1.0 ABSOLUTE MAXIMUM RATINGS

Storage Temperature: -55°C to 150°C  
Operating Temperature: 0°C to +70°C  
Maximum Voltage on any Pin to Substrate: +0.3 volts to -20 volts  
Power Dissipation @ T = 0°C 1.9 watts

### 2.0 POWER SUPPLIES FOR BOTH CHIPS:

V<sub>CC</sub> +5.0 ± 5% volts  
Ground 0.0 volts  
V<sub>GG</sub> -12.0 ± 5% volts  
I<sub>CC</sub> -170 mA maximum  
I<sub>GG</sub> 80 mA maximum

### 3.0 CLOCKS

#### 3.1 CLOCK TIMING (SEE FIGURE 1)

<u>Symbol</u>	<u>Name</u>	<u>MIN</u>	<u>MAX</u>	<u>Units</u>
V <sub>10</sub>	Logic '0'	-12 ± 5%		volts
V <sub>11</sub>	Logic '1'	V <sub>CC</sub> -1.0	V <sub>CC</sub> +0.3	volts
V <sub>0V</sub>	Logic '0' Overshoot to -20V	20		ns
t <sub>DL</sub>	Deadtime @ -1V	70	*	ns
t <sub>R</sub> , t <sub>F</sub>	Rise, Fall Times Logic '1' to -10 V	10	150	ns
t <sub>S</sub>	Time State duration	500		ns
t <sub>W</sub>	Pulsewidth @ -10 V	350		ns
t <sub>T</sub>	Period	1000	2500	ns

\* No circuit design technique shall require a max t<sub>DL</sub>

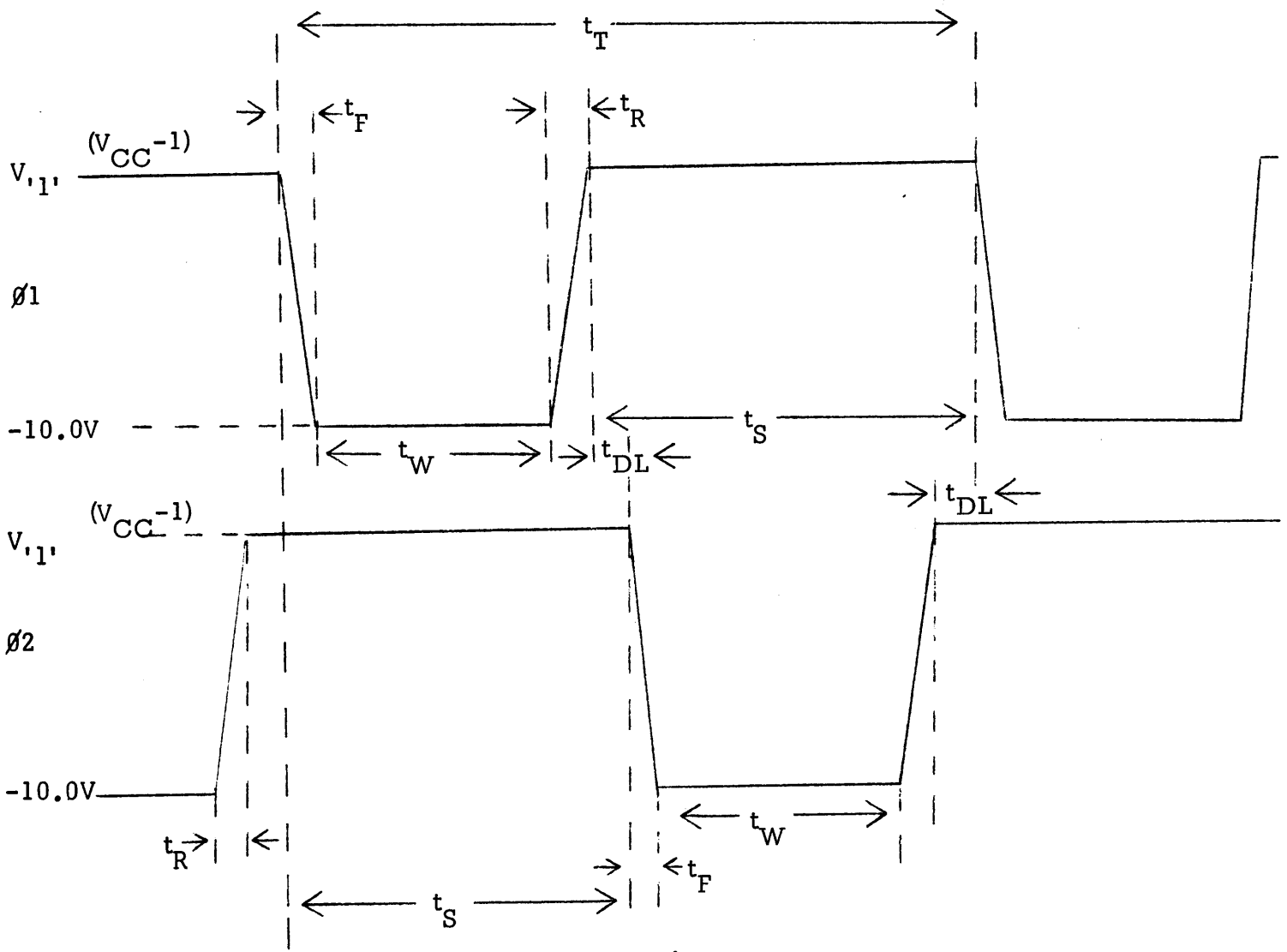


FIGURE 1: CLOCKS

### 3.2 CLOCK LOADING, BOTH CHIPS COMBINED

$\emptyset 1$ :  $C_L = 200$  pF maximum  $I = 1$  mA DC max to Gnd  
           25 pF minimum  
 $\emptyset 2$ :  $C_L = 200$  pF maximum  $I = 1$  mA DC max to Gnd  
           25 pF minimum  
 $C_{CK} = 25$  pf maximum  $I_{CK} = 0$  mA DC  
 $C_{CK}$  = Clock to clock capacitance  
 $I_{CK}$  = Clock to clock current

### 4.0 INPUT LEVELS

#### 4.1 CHIP TO CHIP SIGNALS (K, BC, CI, MBUS0 to MBUS10)

These signals are all driven from one chip to the other

	<u>MIN</u>	<u>MAX</u>	<u>Units</u>
$V_{i1}$	$V_{CC} - 1.2$	$V_{CC} + 0.3$	volts
$V_{i0}$	-10.0	+1.1	volts

#### 4.2 TWO WAY LINES (DE0 - DE7)

When the DE lines are in the Input Mode, the required levels are:

	<u>MIN</u>	<u>MAX</u>	<u>Units</u>
$V_{i1}$	$V_{CC} - 1.2$	$V_{CC} + 0.3$	volts
$V_{i0}$	-10.0	+1.1	volts

#### 4.3 I/O HANDSHAKE LINES (\*I1, \*I2, \*I3, \*RUN, \*AK, & \*DR)

	<u>MIN</u>	<u>MAX</u>	<u>Units</u>
$V_{i1}$	$V_{CC} - 1.2$	$V_{CC} + 0.3$	volts
$V_{i0}$	-10.0	+11	volts

#### 4.4 RESET

	<u>MIN</u>	<u>MAX</u>	<u>Units</u>
$V_{i1}$	$V_{CC} - 1.2$	$V_{CC} + 0.3$	volts
$V_{i0}$	-10.0	+1.1	volts

##### 4.4.1 RESET INPUT PULSEWIDTH

10.0  $\mu$ sec minimum @  $V_{i0}$

4.4.2 RESET PULSE RISE AND FALL TIMES

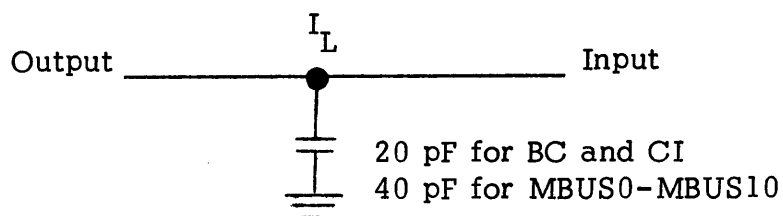
$T_f = 1.0 \mu\text{sec}$  maximum from  $V_{i0}$  to  $V_{i1}$

$T_r$  = not critical

5.0 OUTPUT DRIVE REQUIREMENTS

5.1 BC, CI, MBUS0 to MBUS10

5.1.1 MAXIMUM EXTERNAL LOAD



5.1.2 OUTPUT LEVELS

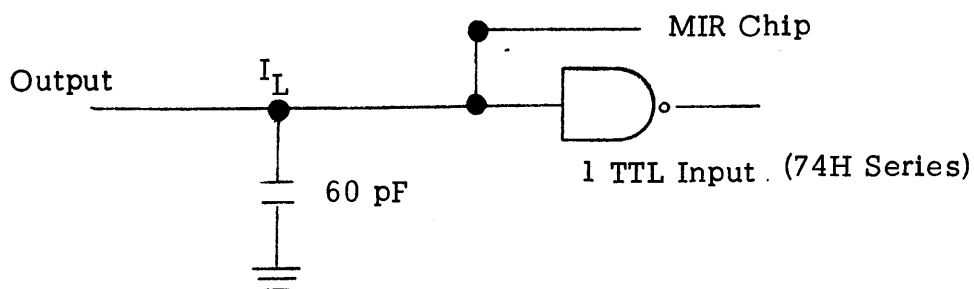
	<u>MIN</u>	<u>MAX</u>	<u>Condition</u>
$V_{i1}$	$V_{CC} - 0.4V$	$V_{CC} + 0.3V$	$I_L = -400 \mu a$
$V_{i0}$	0.0	+0.4	$I_L = 300 \mu a$

5.1.3 DELAY TIMES

(same as 5.2.3)

5.2 DATA EXCHANGE (DE0 - DE7)

5.2.1 MAXIMUM EXTERNAL LOAD



5.2.2 OUTPUT LEVELS

	<u>MIN</u>	<u>MAX</u>	<u>Conditions</u>
$V_{1,1}$	$V_{CC} - 0.4V$	$V_{CC} + 0.3V$	$I_L = -400 \mu a$
$V_{1,0}$	0.0	+0.6	$I_L = 1.65 ma$
$V_{1,0}$			
$V_{1,0}$			

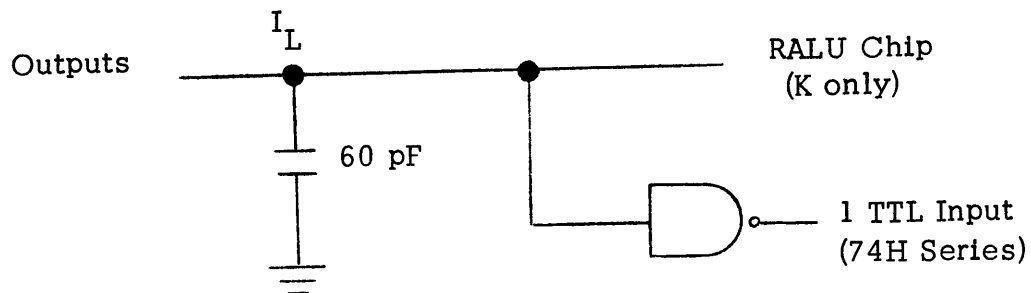
5.2.3 DELAY TIMES

Specified from 90% of negative going edge of  $\phi 1$  or  $\phi 2$ :

750 ns maximum

5.4 I/O HANDSHAKE LINES (\*FRUN, \*SF, \*DR, K)

5.4.1 MAXIMUM EXTERNAL LOADS



#### 5.4.2 OUTPUT LEVELS

	<u>MIN</u>	<u>MAX</u>	<u>Conditions</u>
$V_{11}$	$V_{CC} - 0.4V$	$V_{CC} + 0.3V$	$I_L = -400 \mu A$
$V_{10}$	0.0V	+0.6V	$I_L = 1.65 \text{ ma}$

#### 5.4.3 DELAY TIMES

Specified from 90% of negative going edge of  $\phi 1$  or  $\phi 2$  450ns  
maximum

#### 6.0 INPUT LEAKAGE

6.1 For the Tri-State Drivers (\*SF, DE0 - DE7, MBUS0 - MBUS10)  
in the Tri-State mode and all other inputs except RESET

$$I_L = 10 \mu A \text{ maximum at } V_{IN} = -5.25V$$

6.2 For the RESET input:

$$I_L = 25 \mu A \text{ maximum at } V_{IN} = -17.85V$$

7.0 RESET INPUT CAPACITANCE (MIR CHIP):

10 pF maximum